

Title (en)
THREE-DIMENSIONAL SUSPENDED INTEGRATED MICROSTRUCTURE AND METHOD FOR MAKING SAME

Title (de)
SCHWEBENDE DREIDIMENSIONALE MIKROINTEGRIERTE STRUKTUR UND HERSTELLUNGSVERFAHREN

Title (fr)
MICROSTRUCTURE INTEGREE SUSPENDUE TRIDIMENSIONELLE ET PROCEDE DE FABRICATION

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Application
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Priority

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Abstract (en)
[origin: EP1088785A1] The invention concerns a method for making a suspended microstructure comprising the following steps: forming a masking layer on a substrate top surface; structuring the masking layer to form at least an opening substantially defining the surface of said microstructure and for exposing part of the substrate corresponding to said surface; causing by electrochemical process said exposed semiconductor material to become porous over a predetermined thickness; electropolishing the semiconductor material underlying said microstructure made porous to form a cavity enclosing at least partially said microstructure beneath the masking layer level; and releasing said microstructure made porous to form a microstructure suspended to said substrate by at least a connection portion of its perimeter to provide said microstructure with mobility outside the substrate plane.

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